

LTC1657/LTC1657L

Parallel 16-Bit Rail-to-Rail Micropower DAC

FEATURES

- **16-Bit Monotonic Over Temperature**
- Deglitched Rail-to-Rail Voltage Output: 8nV•s
- I_{CC}: 650μA Typ
- Maximum DNL Error: ±1LSB
- Settling Time: 20µs to ±1LSB
- Built-In Reference: 2.048V (LTC1657) 1.25V (LTC1657L)
- Internal Power-On Reset to Zero Volts
- Asynchronous CLR Pin
- Output Buffer Configurable for Gain of 1 or 2
- Parallel 16-Bit or 2-Byte Double Buffered Interface
- Narrow 28-Lead SSOP Package
- Multiplying Capability

APPLICATIONS

- Instrumentation
- Digital Calibration
- Industrial Process Control
- Automatic Test Equipment
- Communication Test Equipment

DESCRIPTION

The LTC[®]1657/LTC1657L are complete single supply, railto-rail voltage output, 16-bit digital-to-analog converters (DAC) in a 28-pin SSOP or PDIP package. They include a rail-to-rail output buffer amplifier, an internal reference and a double buffered parallel digital interface.

The LTC1657/LTC1657L have separate reference input pins that can be driven by an external reference. The fullscale output can be 1 or 2 times the reference voltage depending on how the X1/X2 pin is connected. The LTC1657 operates from a 4.5V to 5.5V supply and has an onboard 2.048V reference. The LTC1657L operates from a 2.7V to 5.5V supply and has an onboard 1.25V reference.

The LTC1657/LTC1657L are similar to Linear Technology Corporation's LTC1450/LTC1450L 12-bit V_{OUT} DAC family, allowing an upgrade path. They are the only buffered 16-bit parallel DACs in a 28-lead SSOP package and include an onboard reference for stand alone performance.

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ABSOLUTE MAXIMUM RATINGS

(Note 1)
V_{CC} to GND0.5V to 7.5V
TTL Input Voltage, REFHI, REFLO,
X1/X20.5V to 7.5V
V_{OUT} , REFOUT
Operating Temperature Range
LTC1657C/LTC1657LC 0°C to 70°C
LTC1657I/LTC1657LI –40°C to 85°C
Maximum Junction Temperature 125°C
Storage Temperature Range –65°C to 150°C
Lead Temperature (Soldering, 10 sec) 300°C

PACKAGE/ORDER INFORMATION



Consult factory for parts specified with wider operating temperature ranges.

ELECTRICAL CHARACTERISTICS The \bullet denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}$ C. $V_{CC} = 4.5$ V to 5.5V (LTC1657), $V_{CC} = 2.7$ V to 5.5V (LTC1657L), V_{OUT} unloaded, REFOUT tied to REFHI, REFLO tied to GND, X1/X2 tied to GND, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS	
DAC (Note 2)								
	Resolution			16			Bits	
	Monotonicity		•	16			Bits	
DNL	Differential Nonlinearity	Guaranteed Monotonic (Note 3)	•		±0.5	±1	LSB	
INL	Integral Nonlinearity	(Note 3)	•		±4	±12	LSB	
ZSE	Zero Scale Error		•	0		2	mV	
V _{OS}	Offset Error	Measured at Code 200 (LTC1657) Measured at Code 200 (LTC1657L)	•		±0.3 ±0.4	±3 ±4	mV mV	
V _{OS} TC	Offset Error Tempco				±5		μV/°C	
	Gain Error				±2	±16	LSB	
	Gain Error Drift	LTC1657 LTC1657L			0.5 1.0		ppm/°C ppm/°C	
Power Su	pply							
V _{CC}	Positive Supply Voltage	For Specified Performance (LTC1657) For Specified Performance (LTC1657L)	•	4.5 2.7		5.5 5.5	V V	
I _{CC}	Supply Current	(Note 4)	•		650	1200	μA	



ELECTRICAL CHARACTERISTICS The • denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}$ C. $V_{CC} = 4.5$ V to 5.5V (LTC1657), $V_{CC} = 2.7$ V to 5.5V (LTC1657L), V_{OUT} unloaded, REFOUT tied to REFHI, REFLO tied to GND, X1/X2 tied to GND, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
Op Amp D	DC Performance						
	Short-Circuit Current Low	V _{OUT} Shorted to GND			70	120	mA
	Short-Circuit Current High	V _{OUT} Shorted to V _{CC}			80	140	mA
	Output Impedance to GND	Input Code = 0 (LTC1657)			40	120	Ω
		Input Code = 0 (LTC1657L)	•		120	275	Ω
	Output Line Regulation	Input Code = 65535, LTC1657: V_{CC} = 4.5V to 5.5V Input Code = 65535, LTC1657L: V_{CC} = 2.7V to 5.5V	•			4 3	mV/V mV/V
AC Perfor	mance	1	_				
	Voltage Output Slew Rate	(Note 5)	•	±0.3	±0.7		V/µs
	Voltage Output Settling Time	(Note 5) to 0.0015% (16-Bit Settling Time) (Note 5) to 0.012% (13-Bit Settling Time)			20 10		μs μs
	Digital Feedthrough	(Note 6)			0.3		nV∙s
	Midscale Glitch Impulse	DAC Switch Between 8000 _H and 7FFF _H			8		nV∙s
	Output Voltage Noise Using Internal Reference at 1kHz	X1/X2 Tied to V _{OUT} (Notes 8, 9) LTC1657 LTC1657L			165 105		nV/√Hz nV/√Hz
	Output Voltage Noise Using External Reference at 1kHz	X1/X2 Tied to V _{OUT} (Notes 8, 9, 10)			50		nV/√Hz
	Output Voltage Noise Density Using Internal Reference from 0.1Hz to 10Hz	X1/X2 Tied to V _{OUT} (Notes 8, 9)			8		μV _{P-P}
	Refererence Input Multiplying BW				700		kHz
Reference	e Output (REFOUT)						
	Reference Output Voltage	LTC1657 LTC1657L	•	2.036 1.240	2.048 1.250	2.060 1.260	V V
	Reference Output Temperature Coefficient				15		ppm/°C
	Reference Line Regulation	LTC1657: V _{CC} = 4.5V to 5.5V LTC1657L: V _{CC} = 2.7V to 5.5V	•			±1.5 ±1.0	mV/V mV/V
	Reference Load Regulation	Measured at I_{OUT} = 100µA (LTC1657) Measured at I_{OUT} = 100µA (LTC1657L)	•			5 3	mV/A mV/A
	Short-Circuit Current	REFOUT Shorted to GND			50	100	mA
	Reference Output Voltage Noise at 1kHz	LTC1657 LTC1657L			150 90		nV/√Hz nV/√Hz
	Reference Output Voltage Noise Density from 0.1Hz to 10Hz				6		μV _{P-P}
Reference	e Input						
	REFHI, REFLO Input Range	(Note 7) See Applications Information X1/X2 Tied to V _{OUT} X1/X2 Tied to GND	•	0 0		V _{CC} – 1.5 V _{CC} /2	V V
	REFHI Input Resistance	LTC1657 LTC1657L (Relative to REFLO)	•	16 16	25 23		kΩ kΩ



ELECTRICAL CHARACTERISTICS The • denotes specifications which apply over the full operating temperature range $T_A = T_{MIN}$ to T_{MAX} . $V_{CC} = 5V$ (LTC1657), $V_{CC} = 3V$ (LTC1657L), unless otherwise noted.

					LTC1657			LTC1657L		
SYMBOL	PARAMETER	CONDITIONS		MIN	ТҮР	MAX	MIN	ТҮР	MAX	UNITS
Digital I/O										
V _{IH}	Digital Input High Voltage			2.4			2.0			V
V _{IL}	Digital Input Low Voltage					0.8			0.6	V
I _{LEAK}	Digital Input Leakage	$V_{IN} = GND$ to V_{CC}				±10			±10	μA
CIN	Digital Input Capacitance	(Note 7)	•			10			10	pF
Switching	Characteristics									
t _{CS}	CS (MSB or LSB) Pulse Width		•	40			60			ns
t _{WR}	WR Pulse Width		•	40			60			ns
t _{CWS}	CS to WR Setup		•	0			0			ns
t _{CWH}	$\overline{\text{CS}}$ to $\overline{\text{WR}}$ Hold		•	0			0			ns
t _{DWS}	Data Valid to WR Setup		•	40			60			ns
t _{DWH}	Data Valid to WR Hold		•	0			0			ns
t _{LDAC}	LDAC Pulse Width		•	40			60			ns
t _{CLR}	CLR Pulse Width		•	40			60			ns

Note 1: Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

Note 2: External reference REFHI = 2.2V. V_{CC} = 5V (LTC1657).

External reference REFHI = 1.3V. V_{CC} = 3V (LTC1657L).

Note 3: Nonlinearity is defined from code 128 to code 65535 (full scale). See Applications Information.

Note 4: Digital inputs at OV or V_{CC}.

Note 5: DAC switched between all 1s and all 0s. $V_{FS} = 4.096V$.

Note 6: D0 to D15 toggle between all 0s and all 1s with REFHI = 0V, $\overline{\text{CSMSB}} = \overline{\text{CSLSB}} = \overline{\text{WR}} = \overline{\text{LDAC}} = \text{High}$

Note 7: Guaranteed by design. Not subject to test.

Note 8: DAC inputs all 1s.

Note 9: X1/X2 tied to GND, the voltage noise will be a factor of 2 greater. Note 10: Using 2.048V (1.25V) external reference with $3nV/\sqrt{Hz}$ noise at 1kHz for LTC1657/(LTC1657L).



TYPICAL PERFORMANCE CHARACTERISTICS





TYPICAL PERFORMANCE CHARACTERISTICS





TYPICAL PERFORMANCE CHARACTERISTICS



PIN FUNCTIONS

WR (Pin 1): Write Input (Active Low). Used with CSMSB and/or CSLSB to control the input registers. While WR and CSMSB and/or CSLSB are held low, data writes into the input register.

CSLSB (Pin 2): Chip Select Least Significant Byte (Active Low). Used with WR to control the LSB 8-bit input registers. While WR and CSLSB are held low, the LSB byte writes into the LSB input register. Can be connected to CSMSB for simultaneous loading of both sets of input latches on a 16-bit bus.

CSMSB (Pin 3): Chip Select Most Significant Byte (Active Low). Used with WR to control the MSB 8-bit input registers. While WR and CSMSB are held low, the MSB byte writes into the MSB input register. Can be connected to CSLSB for simultaneous loading of both sets of input latches on a 16-bit bus.

D0 to D7 (Pins 4 to 11): Input data for the Least Significant Byte. Written into LSB input register when $\overline{WR} = 0$ and $\overline{CSLSB} = 0$.

D8 to D15 (Pins 12 to 19): Input data for the Most Significant Byte. Written into MSB input register when $\overline{WR} = 0$ and $\overline{CSMSB} = 0$.

GND (Pin 20): Ground.

REFLO (Pin 21): Lower input terminal of the DAC's internal resistor ladder. Typically connected to Analog Ground. An input code of $(0000)_H$ will connect the positive input of the output buffer to this end of the ladder. Can be used to offset the zero scale above ground.

REFHI (Pin 22): Upper input terminal of the DAC's internal resistor ladder. Typically connected to REFOUT. An input code of (FFFF)_H will connect the positive input of the output buffer to 1LSB below this voltage.

REFOUT (Pin 23): Output of the internal reference is 2.048V (LTC1657), 1.25V (LTC1657L). Typically connected to REFHI to drive internal DAC resistor ladder.

 V_{CC} (Pin 24): Positive Power Supply Input. 4.5V \leq V_{CC} \leq 5.5V (LTC1657), 2.7V \leq V_{CC} \leq 5.5V (LTC1657L). Requires a 0.1µF bypass capacitor to ground.

Vout (Pin 25): Buffered DAC Output.

X1/X2 (Pin 26): Gain Setting Resistor Pin. Connect to GND for G = 2 or to V_{OUT} for G = 1. This pin should always be tied to a low impedance source, such as ground or V_{OUT} , to ensure stability of the output buffer when driving capacitive loads.



PIN FUNCTIONS

CLR (Pin 27): Clear Input (Asynchronous Active Low). A low on this pin asynchronously resets all input and DAC registers to 0s.

LDAC (Pin 28): Load DAC (Asynchronous Active Low). Used to asynchronously transfer the contents of the input registers to the DAC register which updates the output voltage. If held low, the DAC register loads data from the input registers which will immediately update V_{OUT}.

CLR	CSMSB	CSLSB	WR	LDAC	FUNCTION	
L	Х	Х	Х	Х	Clears input and DAC registers to zero	
Н	Х	Х	Х	L	L Loads DAC register with contents of input registers	
Н	Х	Х	Х	Н	Freezes contents of DAC register	
Н	L	Н	L	Х	X Writes MSB byte into MSB input register	
Н	Н	L	L	X Writes LSB byte into LSB input register		
Н	L	L	L	X Writes MSB and LSB bytes into MSB and LSB input regis		
Н	Х	Х	Н	X Inhibits write to MSB and LSB input registers		
Н	Н	Х	Х	Х	Inhibits write to MSB input register	
Н	Х	Н	Х	Х	X Inhibits write to LSB input register	
Н	L	L	L	L	L Data bus flows directly through input and DAC registers	

DIGITAL INTERFACE TRUTH TABLE

TIMING DIAGRAM





DEFINITIONS

Resolution (n): Resolution is defined as the number of digital input bits (n). It defines the number of DAC output states (2^n) that divide the full-scale range. Resolution does not imply linearity.

Full-Scale Voltage (V_{FS}): This is the output of the DAC when all bits are set to 1.

Voltage Offset Error (V_{OS}): Normally, the DAC offset is the voltage at the output when the DAC is loaded with all zeros. The DAC can have a true negative offset, but because the part is operated from a single supply, the output cannot go below zero. If the offset is negative, the output will remain near OV resulting in the transfer curve shown in Figure 1.



Figure 1. Effect of Negative Offset

The offset of the part is measured at the code that corresponds to the maximum offset specification:

 $V_{OS} = V_{OUT} - [(Code)(V_{FS})/(2^n - 1)]$

Least Significant Bit (LSB): One LSB is the ideal voltage difference between two successive codes.

 $LSB = G \bullet V_{REF}/65536$

G = 1 for X1/X2 connected to V_{OUT}

G = 2 for X1/X2 connected to GND

Nominal LSBs: (V_{REFOUT} tie to V_{REFHI}, REFLO tie to GND, G = 2)

LTC1657 LSB = $4.096V/65536 = 62.5\mu V$ LTC1657L LSB = $2.5V/65536 = 38.1\mu V$

DAC Transfer Characteristic:

$$V_{OUT} = G \bullet \left(\frac{\text{REFHI} - \text{REFLO}}{65536} \right) (\text{CODE}) + \text{REFLO}$$

 $\label{eq:G} \begin{array}{l} G = 1 \mbox{ for X1/X2 connected to } V_{OUT} \\ G = 2 \mbox{ for X1/X2 connected to GND} \\ CODE = Decimal \mbox{ equivalent of digital input} \\ (0 \leq CODE \leq 65535) \end{array}$

Zero-Scale Error (ZSE): The output voltage when the DAC is loaded with all zeros. Since this is a single supply part, this value cannot be less than 0V.

Integral Nonlinearity (INL): End-point INL is the maximum deviation from a straight line passing through the end points of the DAC transfer curve. Because the part operates from a single supply and the output cannot go below zero, the linearity is measured between full scale and the code corresponding to the maximum offset specification. The INL error at a given input code is calculated as follows:

INL (In LSBs) = $[V_{OUT} - V_{OS} - (V_{FS} - V_{OS}) (code/65535)]$

 V_{OUT} = The output voltage of the DAC measured at the given input code

Differential Nonlinearity (DNL): DNL is the difference between the measured change and the ideal one LSB change between any two adjacent codes. The DNL error between any two codes is calculated as follows:

 $\begin{array}{l} {\sf DNL} = \ (\Delta V_{OUT} - {\sf LSB}) / {\sf LSB} \\ \Delta V_{OUT} = \ {\sf The\ measured\ voltage\ difference\ between\ two\ adjacent\ codes} \end{array}$

Digital Feedthrough: The glitch that appears at the analog output caused by AC coupling from the digital inputs when they change state. The area of the glitch is specified in $nV \bullet s$.



OPERATION

Parallel Interface

The data on the input of the DAC is written into the DAC's input registers when Chip Select (CSLSB and/or CSMSB) and WR are at a logic low. The data that is written into the input registers will depend on which of the Chip Selects are at a logic low (see Digital Interface Truth Table). If WR and CSLSB are both low and CSMSB is high, then only data on the eight LSBs (D0 to D7) is written into the input registers. Similarly, if WR and CSMSB are both low and CSMSB is high, then only data on the eight MSBs (D8 to D15) is written into the input registers. Data is written into both the Least Significant Data Bits (D0 to D7) and the Most Significant Bits (D8 to D15) at the same time if WR, CSLSB and CSMSB are low. If WR is high or both CSMSB and CSLSB are high, then no data is written into the input registers.

Once data is written into the input registers, it can be written into the DAC register. This will update the analog voltage output of the DAC. The DAC register is written by a logic low on LDAC. The data in the DAC register will be held when LDAC is high.

When \overline{WR} , \overline{CSLSB} , \overline{CSMSB} and \overline{LDAC} are all low, the registers are transparent and data on pins D0 to D15 flows directly into the DAC register.

For an 8-bit data bus connection, tie the MSB byte data pins to their corresponding LSB byte pins (D15 to D7, D14 to D6, etc).

Power-On Reset

The LTC1657/LTC1657L have an internal power-on reset that resets all internal registers to 0's on power-up and V_{OUT} pin forces to GND (equivalent to the CLR pin function).

Reference

The LTC1657/LTC1657L include an internal 2.048V/1.25V reference, giving the LTC1657/LTC1657L a full-scale range of 4.096V/2.5V in the gain-of-2 configuration. The onboard reference in the LTC1657/LTC1657L is not internally connected to the DAC's reference resistor string but is provided on an adjacent pin for flexibility. Because the internal reference is not internally connected to the DAC

resistor ladder, an external reference can be used or the resistor ladder can be driven by an external source in multiplying applications. The external reference or source must be capable of driving the 16k (minimum) DAC ladder resistance.

Internal reference output noise can be reduced with a bypass capacitor to ground. (Note: The reference does not require a bypass capacitor to ground for nominal operation.) When bypassing the reference, a small value resistor in series with the capacitor is recommended to help reduce peaking on the output. A 10Ω resistor in series with a 4.7μ F capacitor is optimum for reducing reference generated noise. Internal reference output voltage noise spectral density at 1kHz is typically 150nV/ $\sqrt{\text{Hz}}$ (LTC1657), 90nV/ $\sqrt{\text{Hz}}$ (LTC1657L)

DAC Resistor Ladder

The high and low end of the DAC ladder resistor string (REFHI and REFLO, respectively) are not connected internally on this part. Typically, REFHI will be connected to REFOUT and REFLO will be connected to GND. X1/X2 connected to GND will give the LTC1657/LTC1657L a fullscale output swing of 4.096V/2.5V.

Either of these pins can be driven up to $V_{CC} - 1.5V$ when using the buffer in the gain-of-1 configuration. The resistor string pins can be driven to $V_{CC}/2$ when the buffer is in the gain of 2 configuration. The resistance between these two pins is typically 25k (16k min) (LTC1657), 23k (16k min) (LTC1657L).

Voltage Output

The output buffer for the LTC1657/LTC1657L can be configured for two different gain settings. By tying the X1/X2 pin to GND, the gain is set to 2. By tying the X1/X2 pin to V_{OUT} , the gain is set to unity.

The LTC1657/LTC1657L rail-to-rail buffered output can source or sink 5mA within 500mV of the positive supply voltage or ground at room temperature. The output stage is equipped with a deglitcher that results in a midscale glitch impulse of 8nV • s. The output swings to within a few millivolts of either supply rail when unloaded and has an equivalent output resistance of 40Ω (LTC1657), 120Ω (LTC1657L) when driving a load to the rails.



APPLICATIONS INFORMATION

Rail-to-Rail Output Considerations

In any rail-to-rail DAC, the output swing is limited to voltages within the supply range.

If the DAC offset is negative, the output for the lowest codes limits at OV as shown in Figure 1b.

Similarly, limiting can occur near full scale when the REF pin is tied to $V_{CC}/2$. If $V_{REF} = V_{CC}/2$ and the DAC full-scale error (FSE) is positive, the output for the highest codes limits at V_{CC} as shown in Figure 1c. No full-scale limiting can occur if V_{REF} is less than ($V_{CC} - FSE$)/2.

Offset and linearity are defined and tested over the region of the DAC transfer function where no output limiting can occur.



Figure 2. Effects of Rail-to-Rail Operation On a DAC Transfer Curve. (a) Overall Transfer Function (b) Effect of Negative Offset for Codes Near Zero Scale (c) Effect of Positive Full-Scale Error for Input Codes Near Full Scale When $V_{REF} = V_{CC}/2$



TYPICAL APPLICATIONS

This circuit shows how to make a bipolar output 16-bit DAC with a wide output swing using an LTC1657 and an LT1077. R1 and R2 resistively divide down the LTC1657 output and an offset is summed in using the LTC1657 onboard 2.048V reference and R3 and R4. R5 ensures that

the onboard reference is always sourcing current and never has to sink any current even when V_{OUT} is at full scale. The LT1077 output will have a wide bipolar output swing of -4.096V to 4.096V as shown in the figure below. With this output swing, 1LSB = 125μ V.



A Wide Swing, Bipolar Output 16-Bit DAC



TYPICAL APPLICATIONS

This circuit shows a digitally programmable current source from an external voltage source using an external op amp, an LT1218 and an NPN transistor (2N3440). Any digital word from 0 to 65535 is loaded into the LTC1657 and its output correspondingly swings from 0V to 4.096V. This voltage will be forced across the resistor R_A . If R_A is chosen to be 412 Ω , the output current will range from OmA at zero scale to 10mA at full scale. The minimum voltage for V_S is determined by the load resistor R_L and Q1's V_{CESAT} voltage. With a load resistor of 50 Ω , the voltage source can be 5V.

Digitally Programmable Current Source





PACKAGE DESCRIPTION Dimensions in inches (millimeters) unless otherwise noted.



GN Package 28-Lead Plastic SSOP (Narrow 0.150) (LTC DWG # 05-08-1641)

** DIMENSION DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010" (0.254mm) PER SIDE

GN28 (SSOP) 1098



PACKAGE DESCRIPTION Dimensions in inches (millimeters) unless otherwise noted.



N Package

*THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 INCH (0.254mm)

N28 1098



TYPICAL APPLICATIONS

This circuit shows how to measure negative offset. Since LTC1657/LTC1657L operate on a single supply, if their offset is negative, the output for code 0 limits at 0V. To

measure this negative offset, a negative supply is needed, connect resistor R1 as shown in the figure. The output voltage is the offset when code 0 is loaded in.

Negative Offset Measurement



Although LTC1657 output is up to 4.096V with its internal reference, higher voltages can be achieved with the help of another op amp. The following circuit shows how to increase the output swing of LTC1657 by using an LT1218.

As shown in the configuration, the output of LTC1657 is amplified by 8 for an output swing of 0V to 32.768V, or a convenient 0.5mV/LSB.



A Higher Voltage Output DAC

RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LTC1446(L)	Dual 12-Bit V _{OUT} DACs in SO-8 Package	V _{CC} = 5V (3V), V _{OUT} = 0V to 4.095V (0V to 2.5V)
LTC1450(L)	Single 12-Bit V _{OUT} DACs with Parallel Interface	V _{CC} = 5V (3V), V _{OUT} = 0V to 4.095V (0V to 2.5V)
LTC1458(L)	Quad 12-Bit Rail-to-Rail Output DACs with Added Functionality	V _{CC} = 5V (3V), V _{OUT} = 0V to 4.095V (0V to 2.5V)
LTC1650	Single 16-Bit V _{OUT} Industrial DAC in 16-Pin SO	$V_{CC} = \pm 5V$, Low Power, Deglitched, 4-Quadrant Multiplying V_{OUT}
LTC1654	Dual 14-Bit V _{OUT} DAC	Programmable Speed/Power, SO-8 Footprint
LTC1655(L)	Single 16-Bit V _{OUT} DAC with Serial Interface in SO-8	V _{CC} = 5V (3V), Low Power, Deglitched, V _{OUT} = 0V to 4.096V (0V to 2.5V)
LTC1658	Single 14-Bit V _{OUT} DAC in MSOP Package	2.7V to 5.5V Operation, Low Power

